



# IEEE ITC-Asia 2022

The 6th IEEE International Test Conference in Asia

24-26 August 2022, Taipei, Taiwan

## Call For Papers

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International Test Conference has been a flagship conference in test technology since 1970. In an attempt to stimulate more discussion and interaction between academia and the industry around the globe, ITC-Asia was initiated as a sister conference of ITC in 2017. This year, it is again back to Taipei City, Taiwan. Welcome to join us to immerse ourselves in not only the state-of-the-art test technology but also numerous semiconductor industry forums.

Original papers on, but not limited to, the following areas are invited.

### Topics of Interest include

- Adaptive Test
- ATE Design
- Defect-Based Test
- Design Validation and Debug
- Design-for-Test
- Diagnosis and Failure Analysis
- Emerging Defect Mechanisms
- Fault Tolerance
- HW Security and Security HW
- On-Chip Monitor
- On-Line Test
- Power and Thermal Issues
- Reliability Issues
- System-Level Test and Diagnosis
- Test Compression
- Test Economics
- Test Generation & Fault Simulation
- Yield Analysis and Learning

### Pertaining to systems or underlying technologies including

- 5G/6G/RF
- Analog/Mixed-Signal
- Automotive
- Heterogeneous System-in-Package
- High-Speed I/O
- Internet of Things
- Memory
- MEMS, Sensors
- Photonics Integrated Circuit
- Quantum Devices

### Submissions

Regular paper submissions should be made electronically by PDF manuscripts only, not exceeding 6 pages in IEEE 2-column format (including abstract, figures, tables, and bibliography). A submission will be considered evidence that upon acceptance, at least one author will attend the conference to make the presentation. Authors of accepted papers are also responsible for preparing the final manuscripts in time to be included in the electronic proceedings, which will eventually be published in IEEEExplore Digital Library. At least one full registration to the conference is required for each accepted paper.

### Key Dates

Outstanding papers with extension will be invited to ITC'22.

- Title and abstract submission: ~~April 4, 2022~~ **April 25, 2022**
- Paper submission: ~~April 11, 2022~~ **May 2, 2022**
- Notification of acceptance: June 27, 2022
- Camera ready manuscript: July 24, 2022

2022 ITC-Asia will be a hybrid event.

